

TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (L<sup>2</sup>-π-MOS<sup>2</sup>V)

## 2SK1542

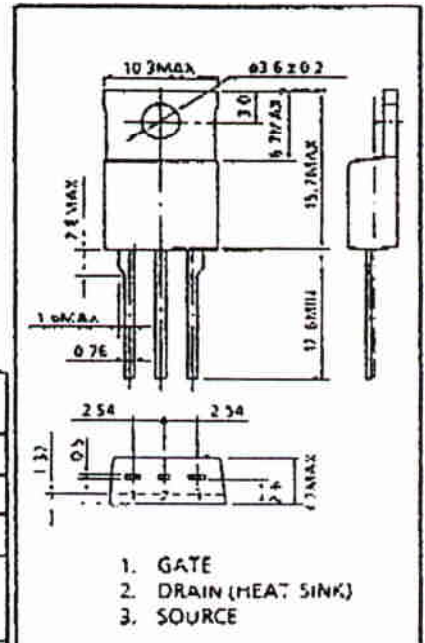
HIGH SPEED SWITCHING APPLICATIONS.  
RELAY DRIVE, MOTOR DRIVE AND DC-DC CONVERTER APPLICATIONS.

INDUSTRIAL APPLICATIONS  
Unit in mm

- 4-Volt Gate Drive
- Low Drain-Source ON Resistance :  $R_{DS(ON)} = 15m\Omega$  (Typ.)
- High Forward Transfer Admittance :  $|Y_{fs}| = 26S$  (Typ.)
- Low Leakage Current :  $I_{DSS} = 100\mu A$  (Max.) @  $V_{DS} = 60V$
- Enhancement-Mode :  $V_{th} = 0.8 \sim 2.0V$  @  $V_{DS} = 10V, I_D = 1mA$

MAXIMUM RATINGS ( $T_a = 25^\circ C$ )

| CHARACTERISTIC                                 | SYMBOL    | RATING   | UNIT       |
|--|-----------|----------|------------|
| Drain-Source Voltage                           | $V_{DS}$  | 60       | V          |
| Drain-Gate Voltage ( $R_{GS} = 20k\Omega$ )    | $V_{DGR}$ | 60       | V          |
| Gate-Source Voltage                            | $V_{GSS}$ | $\pm 20$ | V          |
| Drain Current                                  | DC        | $I_D$    | 45         |
|  | Pulse     | $I_{DP}$ | 180        |
| Drain Power Dissipation ( $T_c = 25^\circ C$ ) | $P_D$     | 125      | W          |
| Channel Temperature                            | $T_{ch}$  | 150      | $^\circ C$ |
| Storage Temperature Range                      | $T_{stg}$ | -55-150  | $^\circ C$ |



|         |          |
|---------|----------|
| JEDEC   | TO-220AB |
| EIAJ    | SC-46    |
| TOSHIBA | 2-10P1B  |

Weight : 2.0g

### THERMAL CHARACTERISTICS

| CHARACTERISTIC                         | SYMBOL         | MAX. | UNIT         |
|--|----------------|------|--------------|
| Thermal Resistance, Channel to Case    | $R_{th(ch-c)}$ | 1.0  | $^\circ C/W$ |
| Thermal Resistance, Channel to Ambient | $R_{th(ch-a)}$ | 83.3 | $^\circ C/W$ |

THIS TRANSISTOR IS AN ELECTROSTATIC SENSITIVE DEVICE.  
PLEASE HANDLE WITH CAUTION.

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ELECTRICAL CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

| CHARACTERISTIC                                  |               | SYMBOL        | TEST CONDITION  | MIN. | TYP. | MAX.      | UNIT          |
|---|---------------|---------------|---|------|------|-----------|---------------|
| Gate Leakage Current                            |               | $I_{GSS}$     | $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$   | —    | —    | $\pm 100$ | nA            |
| Drain Cut-off Current                           |               | $I_{DSS}$     | $V_{DS} = 60\text{V}, V_{GS} = 0\text{V}$   | —    | —    | 100       | $\mu\text{A}$ |
| Drain-Source Breakdown Voltage                  |               | $V_{(BR)DSS}$ | $I_D = 10\text{mA}, V_{GS} = 0\text{V}$   | 60   | —    | —         | V             |
| Gate Threshold Voltage                          |               | $V_{th}$      | $V_{DS} = 10\text{V}, I_D = 1\text{mA}$   | 0.8  | —    | 2.0       | V             |
| Drain-Source ON Resistance                      |               | $R_{DS(ON)}$  | $V_{GS} = 4\text{V}, I_D = 20\text{A}$  | —    | 22   | 35        | m $\Omega$    |
|   |               |               | $V_{GS} = 10\text{V}, I_D = 20\text{A}$   | —    | 15   | 20        |               |
| Forward Transfer Admittance                     |               | $ Y_{fs} $    | $V_{DS} = 10\text{V}, I_D = 20\text{A}$   | 18   | 26   | —         | S             |
| Input Capacitance                               |               | $C_{iss}$     | $V_{DS} = 10\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$  | —    | 2750 | 3500      | pF            |
| Reverse Transfer Capacitance                    |               | $C_{rss}$     |   | —    | 600  | 1000      |               |
| Output Capacitance                              |               | $C_{oss}$     |   | —    | 1500 | 2200      |               |
| Switching Time                                  | Rise Time     | $t_r$         | <p><math>I_D = 20\text{A}</math><br/><math>V_{OUT}</math><br/><math>R_L = 1.5\Omega</math><br/><math>V_{DD} = 30\text{V}</math><br/><math>V_{GS0} = 10\text{V}</math><br/><math>V_{IN} : t_r, t_f &lt; 5\text{ns}</math><br/><math>\text{Duty} \leq 1\%, t_w = 10\mu\text{s}</math></p> | —    | 20   | 40        | ns            |
|   | Furn-on Time  | $t_{on}$      |   | —    | 60   | 120       |               |
|   | Fall Time     | $t_f$         |   | —    | 30   | 160       |               |
|   | Turn-off Time | $t_{off}$     |   | —    | 210  | 400       |               |
| Total Gate Charge (Gate-Source Plus Gate-Drain) |               | $Q_g$         | $V_{DD} = 48\text{V}, V_{GS} = 10\text{V}, I_D = 45\text{A}$  | —    | 200  | 400       | nC            |
| Gate-Source Charge                              |               | $Q_{gs}$      |   | —    | 65   | —         |               |
| Gate-Drain ("Miller") Charge                    |               | $Q_{gd}$      |   | —    | 135  | —         |               |

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_a = 25^\circ\text{C}$ )

| CHARACTERISTIC                   | SYMBOL    | TEST CONDITION                            | MIN. | TYP. | MAX. | UNIT          |
|----------------------------------|-----------|---|------|------|------|---------------|
| Continuous Drain Reverse Current | $I_{DR}$  | —   | —    | —    | 45   | A             |
| Pulse Drain Reverse Current      | $I_{DRP}$ | —   | —    | —    | 130  | A             |
| Diode Forward Voltage            | $V_{DSF}$ | $I_{DR} = 45\text{A}, V_{GS} = 0\text{V}$ | —    | —    | -2.0 | V             |
| Reverse Recovery Time            | $t_{rr}$  | $I_{DR} = 45\text{A}, V_{GS} = 0\text{V}$ | —    | 160  | —    | ns            |
| Reverse Recovered Charge         | $Q_{rr}$  | $dI_{DR}/dt = 50\text{A}/\mu\text{s}$     | —    | 0.2  | —    | $\mu\text{C}$ |



